



bestirpower

# BCZ120N80M1

## N-Channel Silicon Carbide Power MOSFET

1200 V, 30 A, 80 mΩ

### Features

- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Pb-free, Halogen Free, and RoHS Compliant

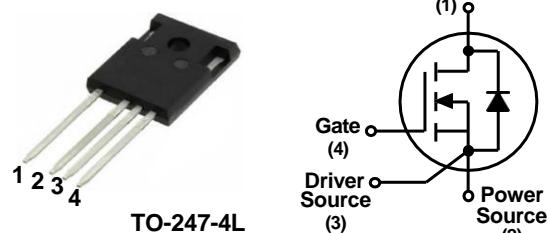
### Benefits

- System efficiency improvement
- Higher frequency applicability
- Increased power density
- Reduced cooling effort

### Applications

- Solar inverter
- EV charging station
- UPS
- Industrial power supply

$BV_{DSS}, T_c=25^\circ C$	$I_D, T_c=25^\circ C$	$R_{DS(on),typ}$	$Q_{g,typ}$
1200 V	30 A	80 mΩ	52 nC



### Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter		Value	Unit
$V_{DSS}$	Drain to Source Voltage		1200	V
$V_{GS}$	Gate to Source Voltage (DC)		-10 / +22	V
$V_{GSop}$	Recommended Operation Value		-5 / +18	V
$I_D$	Drain Current	Continuous ( $T_c = 25^\circ C$ )	30	A
		Continuous ( $T_c = 100^\circ C$ )	21	
$I_{DM}$	Drain Current	Pulsed (Note1)	80	A
$P_D$	Power Dissipation	( $T_c = 25^\circ C$ )	150	W
		Derate Above 25°C	1.00	W/°C
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to 175	°C
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds		260	°C

※Note 1 : Limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{JC}$	Thermal Resistance, Junction to Case, Max.	1.00	°C/W
$R_{JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

### Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
BCZ120N80M1	BCZ120N80M1	TO247-4	Tube	30 units

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 1 \text{ mA}$	1200			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		1	100	$\mu\text{A}$
		$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 175^\circ\text{C}$		5		
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}} = +22 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			+100	$\text{nA}$
		$V_{\text{GS}} = -10 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			-100	

**On Characteristics**

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_D = 5.0 \text{ mA}$ (tested after $V_{\text{GS}} = 22 \text{ V}, 1 \text{ ms pulse}$ )	2.0	3.0	4.5	V
$R_{\text{DS(on)}}$	Static Drain to Source On Resistance	$V_{\text{GS}} = 18 \text{ V}, I_D = 15 \text{ A}$		80	110	$\text{m}\Omega$
		$V_{\text{GS}} = 18 \text{ V}, I_D = 15 \text{ A}, T_J = 175^\circ\text{C}$		128		
$g_{\text{fs}}$	Transconductance	$V_{\text{DS}} = 20 \text{ V}, I_D = 15 \text{ A}$		11.4		S

**Dynamic Characteristics**

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 250 \text{ kHz}$		880		$\text{pF}$
$C_{\text{oss}}$	Output Capacitance			64		
$C_{\text{rss}}$	Reverse Capacitance			5		
$E_{\text{oss}}$	Stored Energy in Output Capacitance	$V_{\text{DS}} = 0 \text{ V} \text{ to } 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		26		$\mu\text{J}$
$C_{\text{o(er)}}$	Energy Related Output Capacitance			80		
$C_{\text{o(tr)}}$	Time Related Output Capacitance			142		
$Q_{\text{g(tot)}}$	Total Gate Charge	$V_{\text{DS}} = 800 \text{ V}, I_D = 15 \text{ A}, V_{\text{GS}} = -5 \text{ V} / 18 \text{ V},$ $\text{Inductive load}$		52		$\text{nC}$
$Q_{\text{gs}}$	Gate to Source Charge			13		
$Q_{\text{gd}}$	Gate to Drain "Miller" Charge			17		
$R_G$	Internal Gate Resistance	$f = 1 \text{ MHz}$		4.0		$\Omega$

**Switching Characteristics**

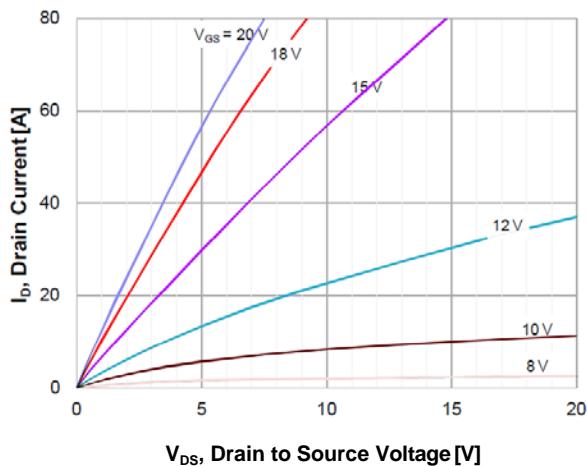
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}} = 800 \text{ V}, I_D = 15 \text{ A}, V_{\text{GS}} = -5 \text{ V} / 18 \text{ V}, R_G = 2 \Omega,$ $\text{FWD : BCH120S010D1, Inductive load}$		14		$\text{ns}$
$t_r$	Turn-On Rise Time			9		
$t_{\text{d(off)}}$	Turn-Off Delay Time			24		
$t_f$	Turn-Off Fall Time			8		
$E_{\text{on}}$	Turn-on Switching Energy			75		
$E_{\text{off}}$	Turn-off Switching Energy			47		
$E_{\text{tot}}$	Total Switching Energy			122		

**Source-Drain Diode Characteristics**

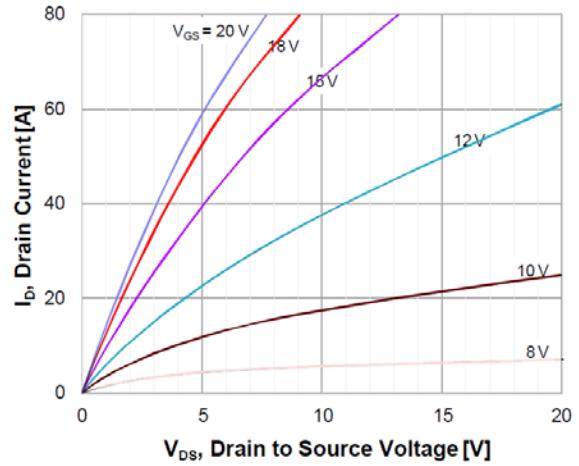
$I_S$	Maximum Continuous Diode Forward Current			30		$\text{A}$
$I_{\text{SM}}$	Maximum Pulsed Diode Forward Current			80		
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}} = -5 \text{ V}, I_{\text{SD}} = 15 \text{ A}$		4.1		$\text{V}$
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{DD}} = 800 \text{ V}, I_{\text{SD}} = 15 \text{ A},$ $dI_F/dt = 3000 \text{ A}/\mu\text{s}, \text{Includes } Q_{\text{oss}}$		12		$\text{ns}$
$Q_{\text{rr}}$	Reverse Recovery Charge			122		

## Typical Performance Characteristics

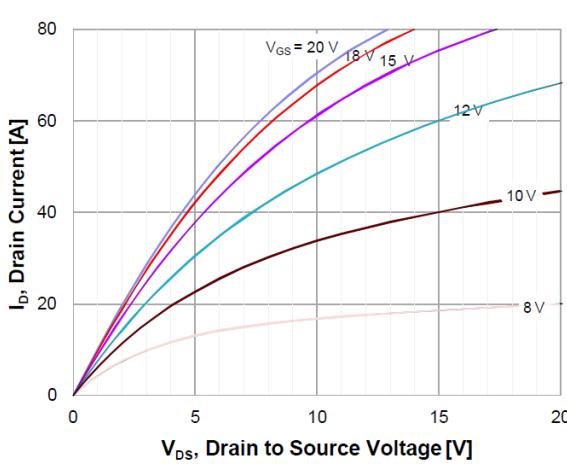
**Figure 1. On-Region Characteristics  $T_J = -40^\circ\text{C}$**



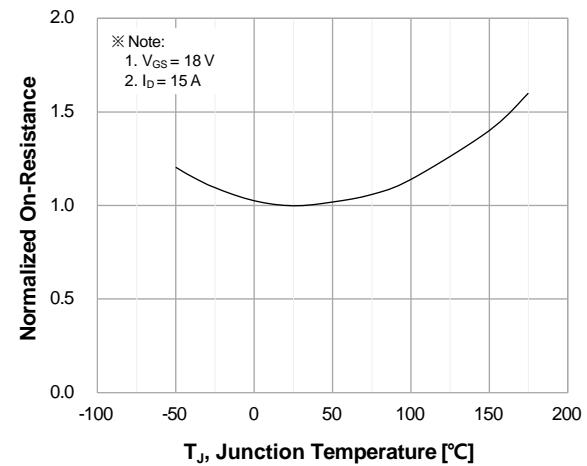
**Figure 2. On-Region Characteristics  $T_J = 25^\circ\text{C}$**



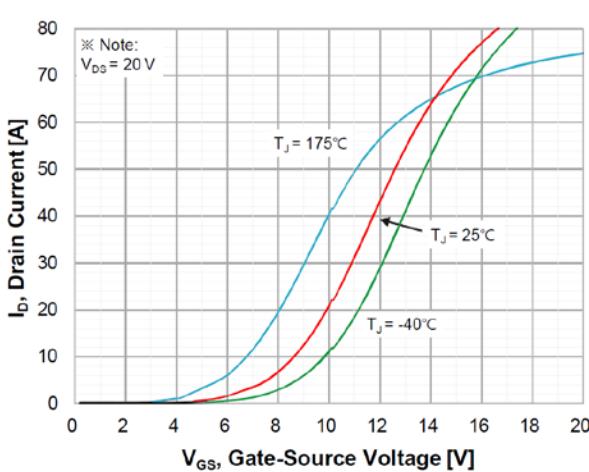
**Figure 3. On-Region Characteristics  $T_J = 175^\circ\text{C}$**



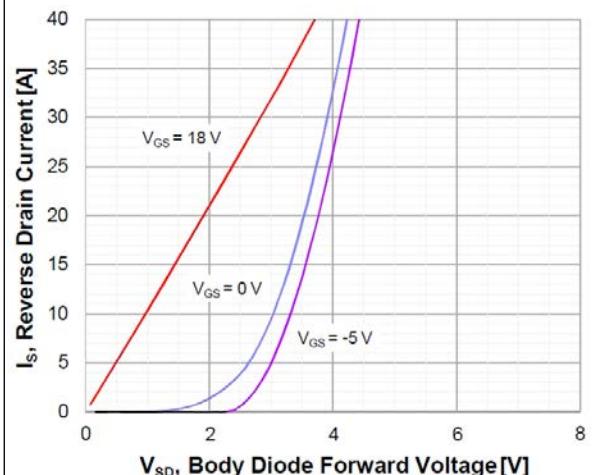
**Figure 4. Normalized On-Resistance Characteristics vs. Temperature**



**Figure 5. Transfer Characteristics**

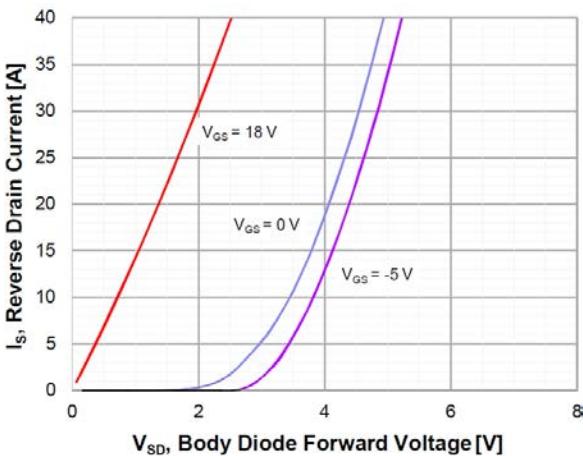


**Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = -40^\circ\text{C}$**

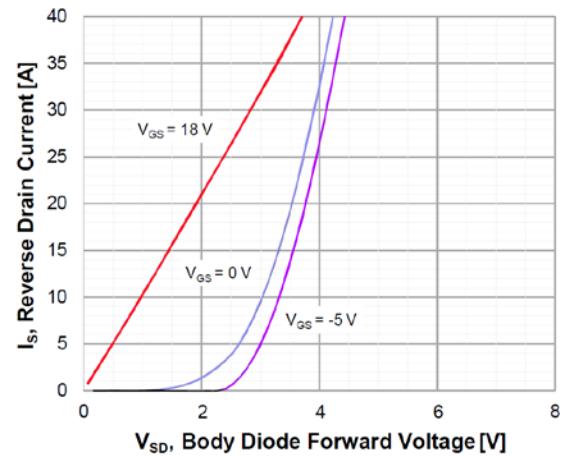


## Typical Performance Characteristics

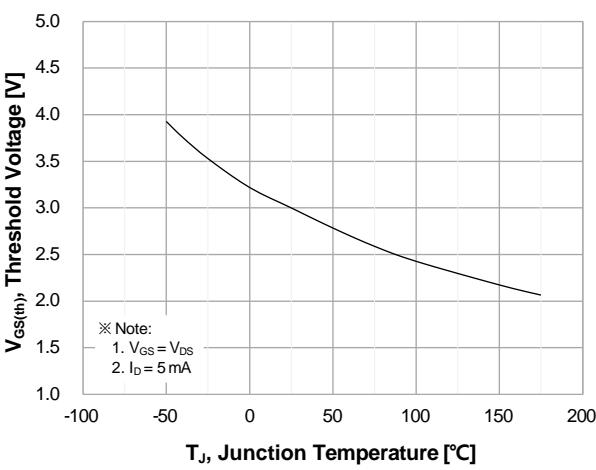
**Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 25^\circ\text{C}$**



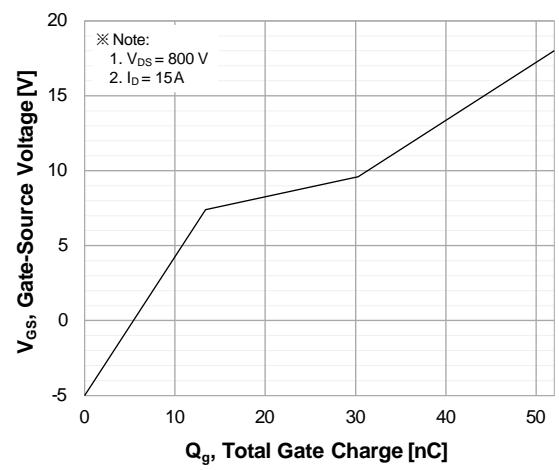
**Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 175^\circ\text{C}$**



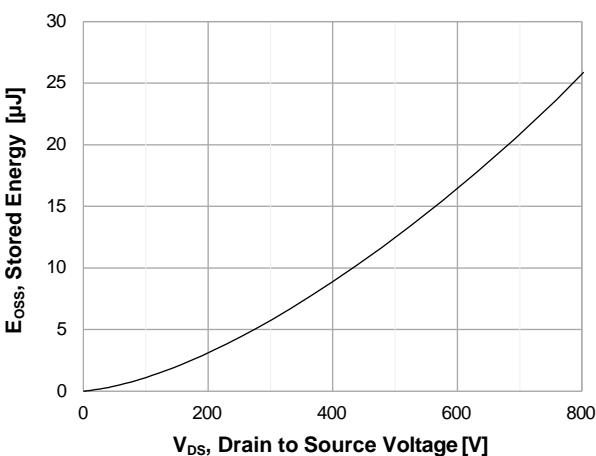
**Figure 9. Threshold Voltage vs. Temperature**



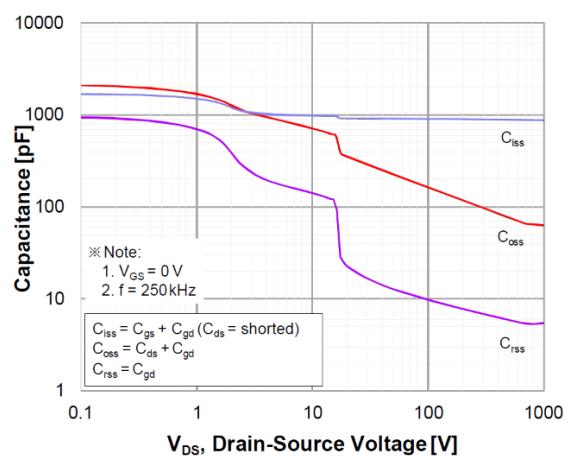
**Figure 10. Gate Charge Characteristics**



**Figure 11. Stored Energy in Output Capacitance**

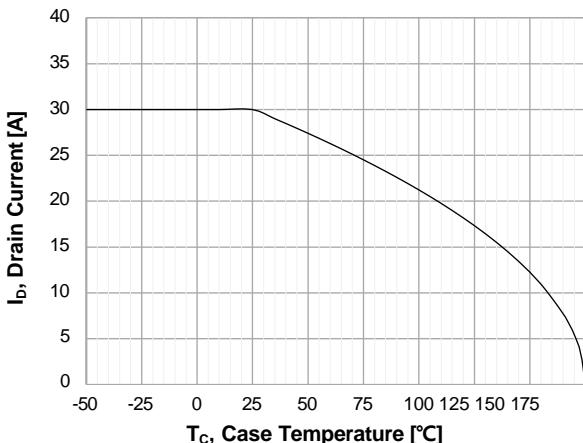


**Figure 12. Capacitance Characteristics**

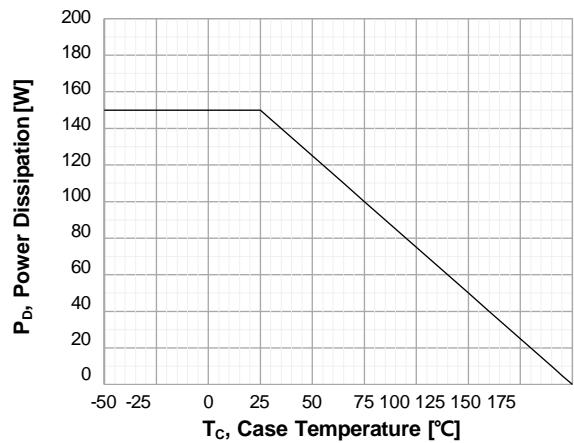


## Typical Performance Characteristics

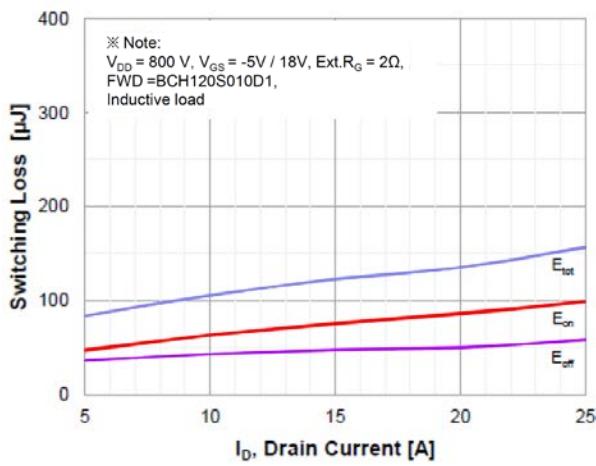
**Figure 13. Continuous Drain Current Derating vs. Case Temperature**



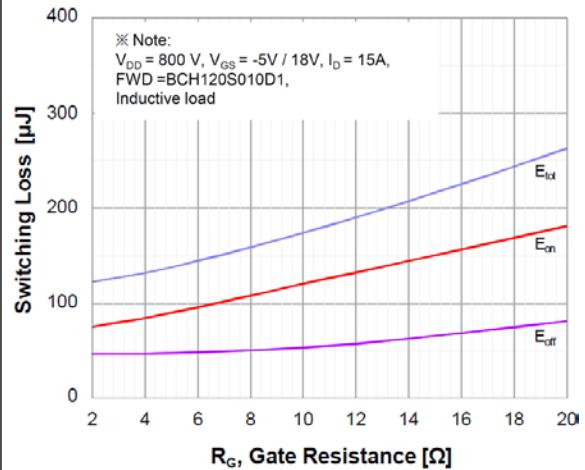
**Figure 14. Maximum Power Dissipation Derating vs. Case Temperature**



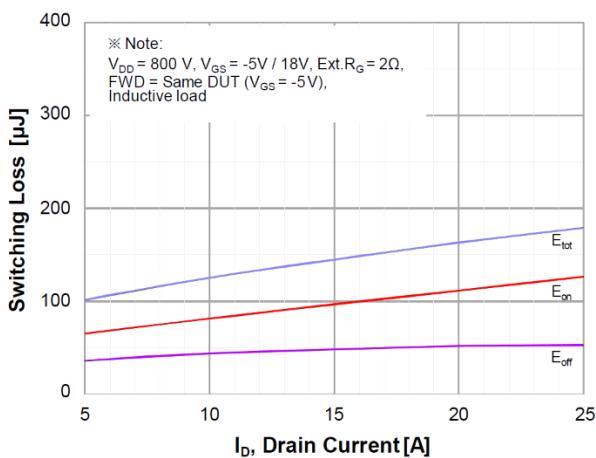
**Figure 15. Typ. Switching Losses vs. Drain Current**



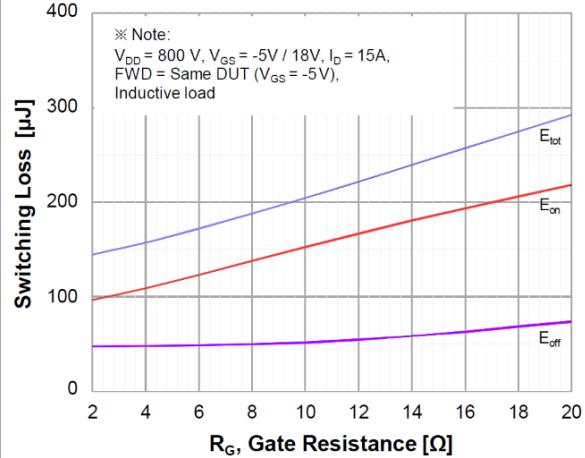
**Figure 16. Typ. Switching Losses vs. Gate Resistance**



**Figure 17. Typ. Switching Losses vs. Drain Current**

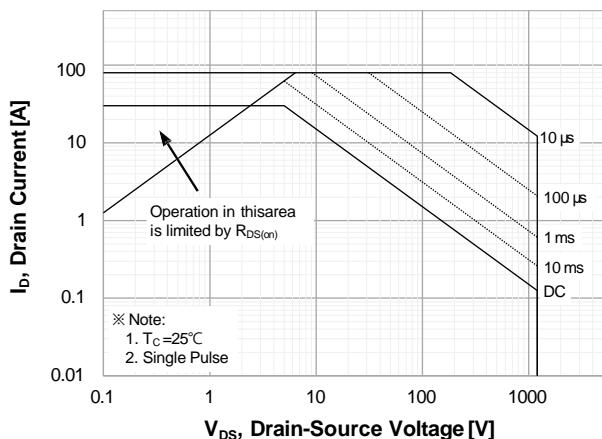


**Figure 18. Typ. Switching Losses vs. Gate Resistance**

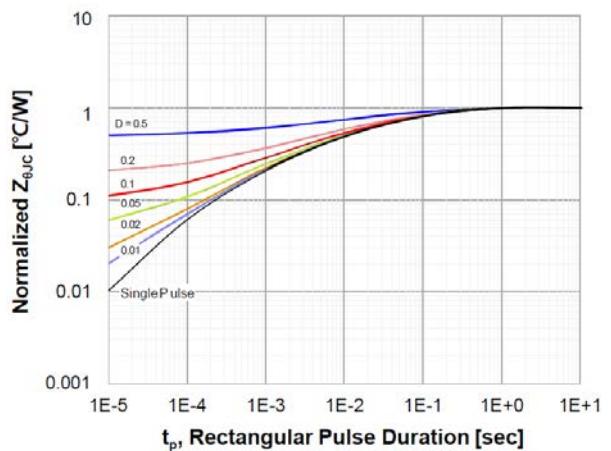


### Typical Performance Characteristics

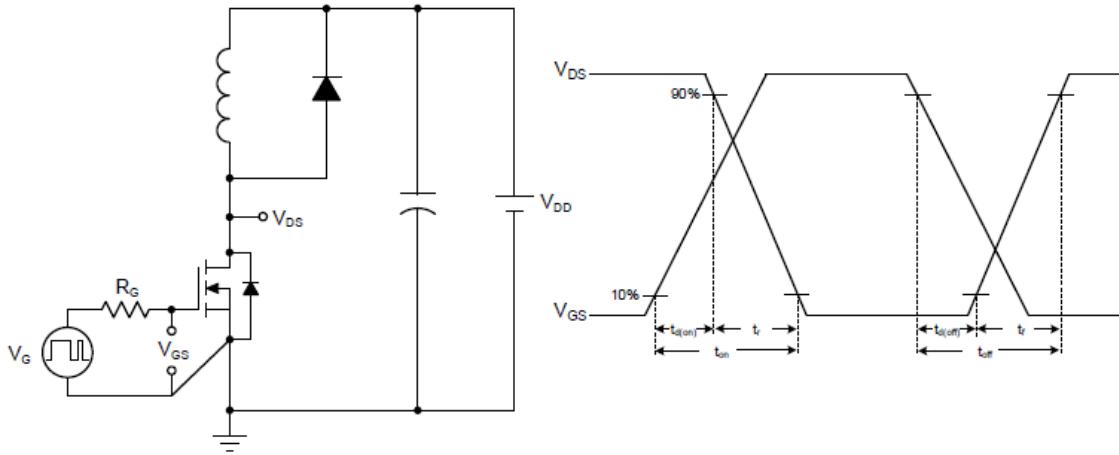
**Figure 19. Maximum Safe Operating Area**



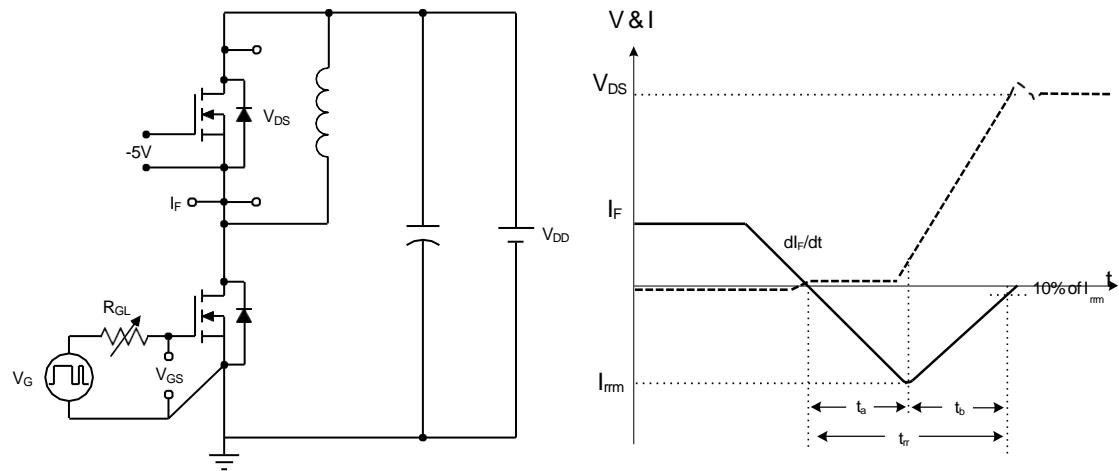
**Figure 20. Transient Thermal Response Curve**



**Figure 21. Inductive Load Switching Test Circuit and Waveforms**

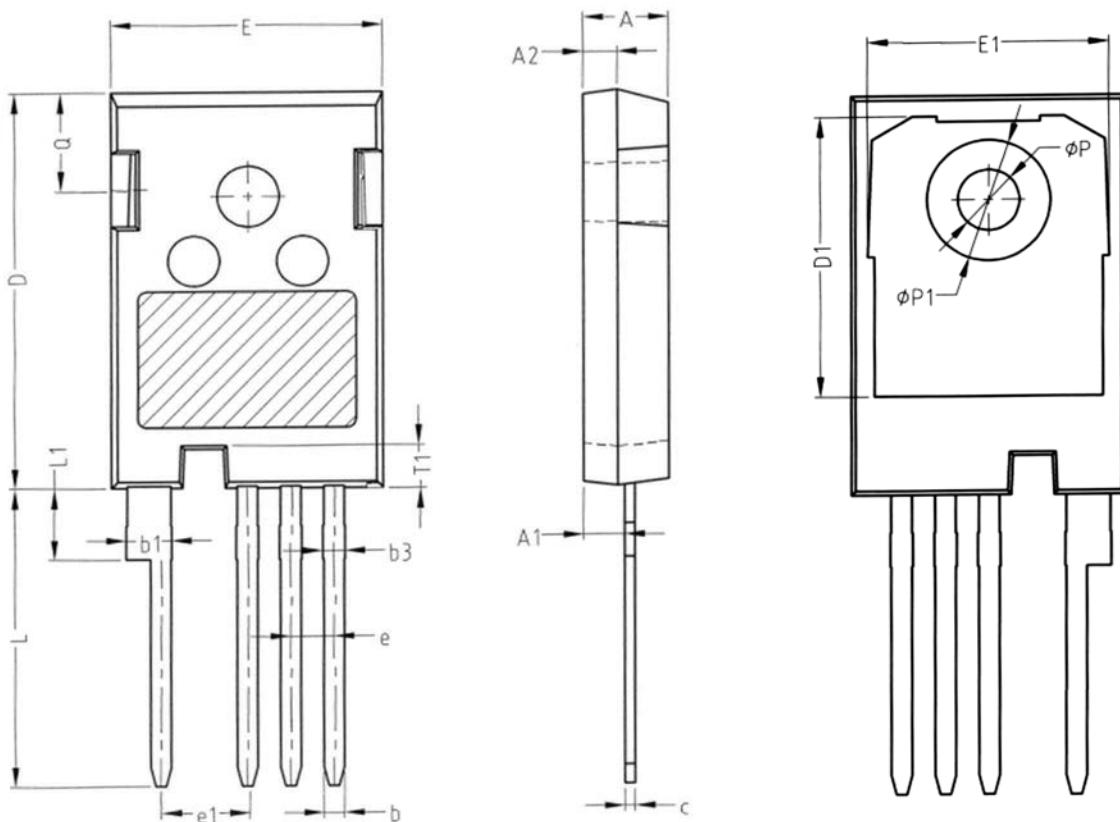


**Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms**



## Package Outlines

## TO247-4



SYMBOL	NM		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.80	2.00	2.20
b	1.06	1.21	1.36
b1	2.33	2.63	2.93
b3	1.07	1.30	1.60
c	0.51	0.61	0.75
D	23.30	23.45	23.60
D1	16.25	16.55	16.85
E	15.74	15.94	16.14
E1	13.72	14.02	14.32
T1	2.35	2.50	2.65
e	2.54 BSC		
e1	5.08 BSC		
Q	5.49	5.79	6.09
L	17.27	17.57	17.87
L1	3.99	4.19	4.39
Φp	3.40	3.60	3.80
Φp1	7.19 REF		

\* Dimensions in millimeters

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